# **MOSFET** – SiC Power, Single N-Channel, TO247-4L

1200 V, 20 mΩ, 102 A

# NTH4L020N120SC1

#### Features

- Typ.  $R_{DS(on)} = 20 \text{ m}\Omega$
- Ultra Low Gate Charge ( $Q_{G(tot)} = 220 \text{ nC}$ )
- High Speed Switching with Low Capacitance ( $C_{oss} = 258 \text{ pF}$ )
- 100% Avalanche Tested
- $T_J = 175^{\circ}C$
- This Device is Pb-Free and is RoHS Compliant

#### **Typical Applications**

- UPS
- DC/DC Converter
- Boost Inverter

#### **MAXIMUM RATINGS** (T<sub>J</sub> = $25^{\circ}$ C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V <sub>DSS</sub>	1200	V
Gate-to-Source Voltage	Gate-to-Source Voltage			-15/+25	V
Recommended Operation Values T <sub>C</sub> < 1 of Gate-to-Source Voltage		T <sub>C</sub> < 175°C	V <sub>GSop</sub>	-5/+20	V
Continuous Drain Current (Note 2)	Steady T <sub>C</sub> = 25°C State		۱ <sub>D</sub>	102	A
Power Dissipation (Note 2)			PD	510	W
Continuous Drain Current (Notes 1, 2)	Steady State	T <sub>C</sub> = 100°C	۱ <sub>D</sub>	84	A
Power Dissipation (Notes 1, 2)			PD	255	W
Pulsed Drain Current (Note 3)	$T_A = 25^{\circ}C$		I <sub>DM</sub>	408	A
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	–55 to +175	°C
Source Current (Body Diode)			I <sub>S</sub>	46	А
Single Pulse Drain-to-Source Avalanche Energy ( $I_{L(pk)} = 23 \text{ A}, L = 1 \text{ mH}$ ) (Note 4)			E <sub>AS</sub>	264	mJ
Maximum Lead Temperature for Soldering (1/8" from case for 5 s)			ΤL	300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

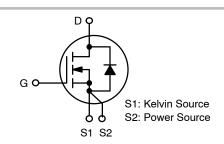
- 1. JA is constant value to follow guide table of LV/HV discrete final datasheet generation.
- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 3. Repetitive rating, limited by max junction temperature.
- 4. EAS of 264 mJ is based on starting  $T_J$  = 25°C; L = 1 mH, I<sub>AS</sub> = 23 A, V<sub>DD</sub> = 120 V, V<sub>GS</sub> = 18 V.



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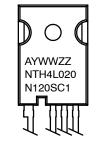
V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
1200 V	28 mΩ @ 20 V	102 A



**N-CHANNEL MOSFET** 



#### MARKING DIAGRAM



A = Assembly Location

Y = Year

WW = Work Week

ZZ = Lot Traceability

NTH4L020N120SC1 = Specific Device Code

#### **ORDERING INFORMATION**

Device	Package	Shipping
NTH4L020N120SC1	TO247-4L	30 ea / Tube

#### THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Мах	Unit
Junction-to-Case - Steady State (Note 2)	$R_{\theta JC}$	0.3	°C/W
Junction-to-Ambient - Steady State (Notes 1, 2)	$R_{\theta JA}$	40	

#### **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise specified)

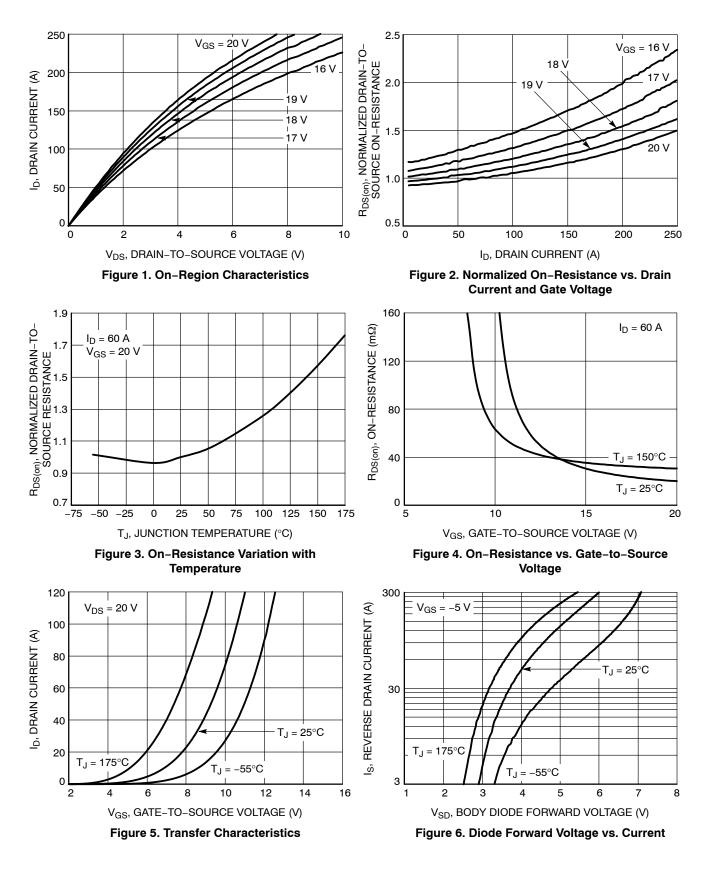
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 1 mA	1200	-	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /T <sub>J</sub>	$I_D = 1 \text{ mA}$ , referenced to 25°C	-	0.5	-	V/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS} = 0 V$ , $T_{J} = 25^{\circ}C$	-	-	100	μA
		V <sub>DS</sub> = 1200 V T <sub>J</sub> = 175°C	-	-	1	mA
Gate-to-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = +25/-15 V, V <sub>DS</sub> = 0 V	-	-	±1	μA
ON CHARACTERISTICS (Note 3)		1				
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 20 mA	1.8	2.7	4.3	V
Recommended Gate Voltage	V <sub>GOP</sub>		-5	-	+20	V
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 20 V, I <sub>D</sub> = 60 A, T <sub>J</sub> = 25°C	-	20	28	mΩ
		V <sub>GS</sub> = 20 V, I <sub>D</sub> = 60 A, T <sub>J</sub> = 175°C	_	37	50	
Forward Transconductance	<b>9</b> FS	V <sub>DS</sub> = 20 V, I <sub>D</sub> = 60 A	_	3.6	-	S
CHARGES, CAPACITANCES & GATE RES	SISTANCE	1				
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> = 0 V, f = 1 MHz, V <sub>DS</sub> = 800 V	-	2943	-	pF
Output Capacitance	C <sub>OSS</sub>		_	258	-	
Reverse Transfer Capacitance	C <sub>RSS</sub>		_	24	-	
Total Gate Charge	Q <sub>G(TOT)</sub>	V <sub>GS</sub> = -5/20 V, V <sub>DS</sub> = 600 V,	-	220	_	nC
Threshold Gate Charge	Q <sub>G(TH)</sub>	I <sub>D</sub> = 80 A	_	33	-	
Gate-to-Source Charge	Q <sub>GS</sub>		_	66	_	
Gate-to-Drain Charge	Q <sub>GD</sub>		_	63	-	
Gate-Resistance	R <sub>G</sub>	f = 1 MHz	_	1.6	_	Ω
SWITCHING CHARACTERISTICS, VGS =	10 V					
Turn-On Delay Time	t <sub>d(ON)</sub>	V <sub>GS</sub> = -5/20 V,	-	21.6	35	ns
Rise Time	t <sub>r</sub>	· V <sub>DS</sub> = 800 V, I <sub>D</sub> = 80 A,	_	21	34	
Turn-Off Delay Time	t <sub>d(OFF)</sub>	$R_G = 2 \Omega$ inductive load	-	41	66	
Fall Time	t <sub>f</sub>	Inductive load	_	10	20	
Turn–On Switching Loss	E <sub>ON</sub>		_	494	_	μJ
Turn–Off Switching Loss	E <sub>OFF</sub>		-	397	-	
Total Switching Loss	E <sub>tot</sub>		-	891	-	
DRAIN-SOURCE DIODE CHARACTERIS		1	4			
Continuous Drain-Source Diode Forward Current	I <sub>SD</sub>	$V_{GS}$ = -5 V, T <sub>J</sub> = 25°C	-	-	46	Α
Pulsed Drain-Source Diode Forward Current (Note 3)	I <sub>SDM</sub>		_	-	408	
Forward Diode Voltage	V <sub>SD</sub>	$V_{GS}$ = -5 V, I <sub>SD</sub> = 30 A, T <sub>J</sub> = 25°C	-	3.7	-	V
Reverse Recovery Time	t <sub>RR</sub>	$V_{GS} = -5/20 \text{ V}, I_{SD} = 80 \text{ A},$	-	30	-	ns
Reverse Recovery Charge	Q <sub>RR</sub>	dI <sub>S</sub> /dt = 1000 A/µs	_	225	_	nC

### **ELECTRICAL CHARACTERISTICS** ( $T_J$ = 25°C unless otherwise specified) (continued)

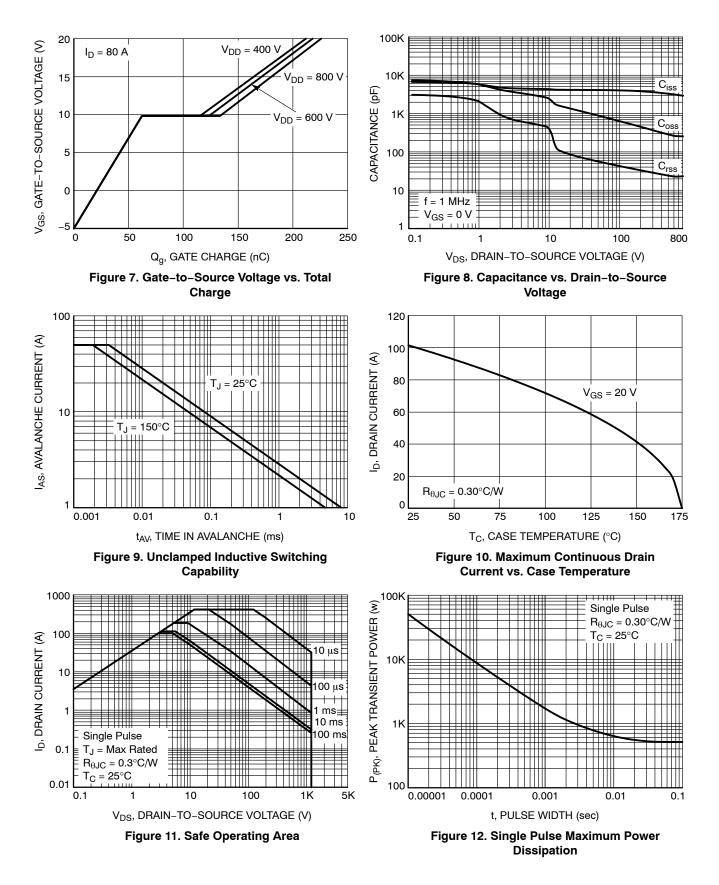
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
DRAIN-SOURCE DIODE CHARACTERISTICS						
Reverse Recovery Energy	E <sub>REC</sub>	$V_{GS} = -5/20 \text{ V}, I_{SD} = 80 \text{ A},$	-	16	-	μJ
Peak Reverse Recovery Current	I <sub>RRM</sub>	dl <sub>S</sub> /dt = 1000 A/µs	-	15	-	А
Charge time	Та		-	16	-	ns
Discharge time	Tb		-	15	-	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### **TYPICAL CHARACTERISTICS**



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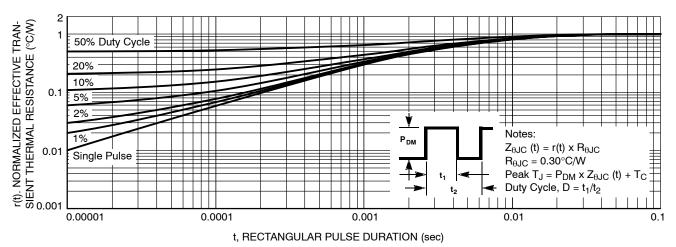
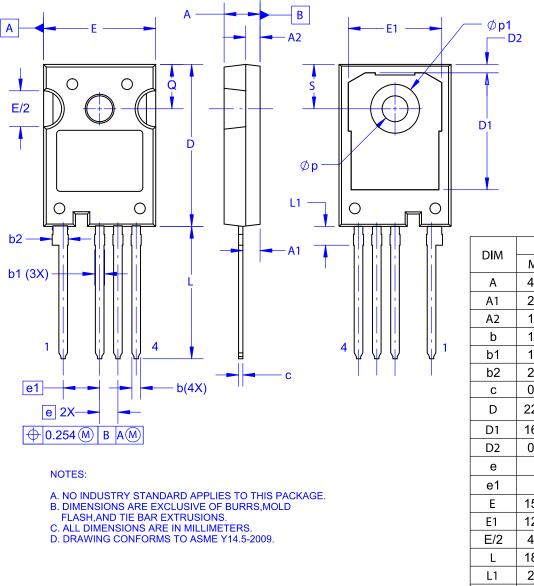


Figure 13. Junction-to-Ambient Thermal Response



TO-247-4LD CASE 340CJ ISSUE A

DATE 16 SEP 2019



	MILLIMETERS				
DIM	MIN	NOM	MAX		
А	4.80	5.00	5.20		
A1	2.10	2.40	2.70		
A2	1.80	2.00	2.20		
b	1.07	1.20	1.33		
b1	1.20	1.40	1.60		
b2	2.02	2.22	2.42		
С	0.50	0.60	0.70		
D	22.34	22.54	22.74		
D1	16.00	16.25	16.50		
D2	0.97	1.17	1.37		
е	2.54 BSC				
e1	Ę	5.08 BSC	2		
Е	15.40	15.60	15.80		
E1	12.80	13.00	13.20		
E/2	4.80	5.00	5.20		
L	18.22	18.42	18.62		
L1	2.42	2.62	2.82		
р	3.40	3.60	3.80		
p1	6.60	6.80	7.00		
Q	5.97	6.17	6.37		
S	5.97	6.17	6.37		

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